

## SOT-23 Plastic-Encapsulate MOSFETS

### Features

- $V_{DS} = -30V$
- $I_D = -4.2A$
- $R_{DS(on)} @ V_{GS} = -10V < 65m\Omega$
- $R_{DS(on)} @ V_{GS} = -4.5V < 75m\Omega$
- $R_{DS(on)} @ V_{GS} = -2.5V < 90m\Omega$
- Trench Power LV MOSFET technology
- High Speed switching

**Drain-source Voltage**

-30 V

**Drain Current**

-4.2 Ampere

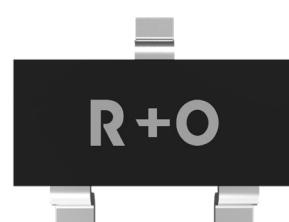
### Applications

- Battery protection
- Load switch
- Power management

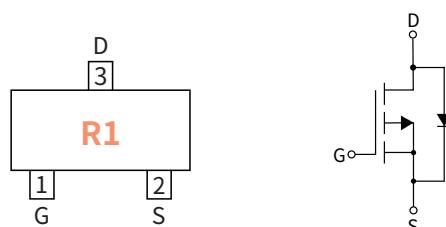
### Mechanical Data

- Case: SOT-23  
Molding compound meets UL 94V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

**SOT-23**



### Function Diagram



### Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE
Drain-source Voltage	$V_{DS}$	V	-30
Gate-source Voltage	$V_{GS}$	V	$\pm 12$
Drain Current	$I_D$	A	-4.2
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	A	-27
Total Power Dissipation <sup>(2)</sup>	$P_D$	W	0.35
Junction temperature	$T_J$	°C	-55 ~ +150
Storage temperature	$T_{stg}$	°C	-55 ~ +150
Thermal Resistance Junction-to-Ambient @ Steady State <sup>(2)</sup>	$R_{\theta JA}$	°C / W	357

### Ordering Information

PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
SOT-23	R1	0.008	3000	45000	180000	7"

### ● Static Parameter Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	V	-30	—	—
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V	μA	—	—	-1.0
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> =0V	nA	—	—	±100
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	V	-0.7	-0.9	-1.3
Static Drain-Source On-Resistance <sup>(3)</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.2A	mΩ	—	50	65
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-4.0A		—	60	75
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> =-1.0A		—	75	90
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5.0V, I <sub>D</sub> =-5.0A	S	7.0	—	—
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.0A, V <sub>GS</sub> =0V	V	—	—	-1.0
Maximum Body-Diode Continuous Current	I <sub>S</sub>	—	A	—	—	-1.0

### ● Dynamic Parameters (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHZ	pF	—	954	—
Output Capacitance	C <sub>oss</sub>			—	115	—
Reverse Transfer Capacitance	C <sub>rss</sub>			—	77	—

### ● Switching Parameters (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =3.6Ω, R <sub>GEN</sub> =6.0Ω		—	—	6.3
Turn-on Rise Time	t <sub>r</sub>			—	—	3.2
Turn-off Delay Time	t <sub>D(off)</sub>			—	—	38.2
Turn-off fall Time	t <sub>f</sub>			—	—	12

Note :

(1)Repetitive rating, pulse width limited by junction temperature T<sub>J(Max)</sub>=150°C . Ratings are based on low frequency and duty cycles to keep initial T<sub>j</sub>=25°C .(2)The value of P<sub>d</sub> and R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C .

(3)Pulse test: Pulse width ≤ 300us, duty cycle ≤ 2%.

## ● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

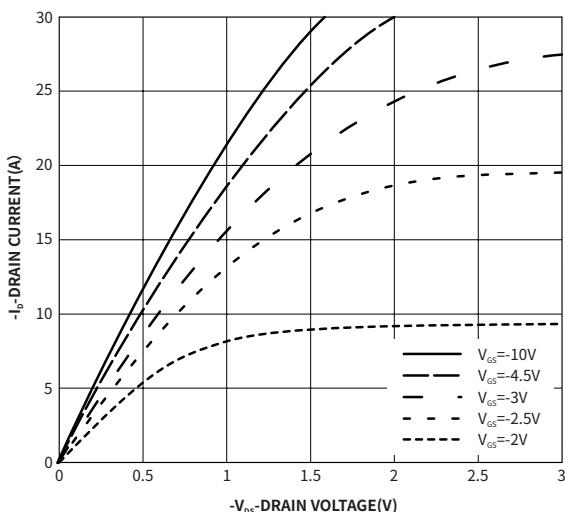


Fig.1 Output Characteristics

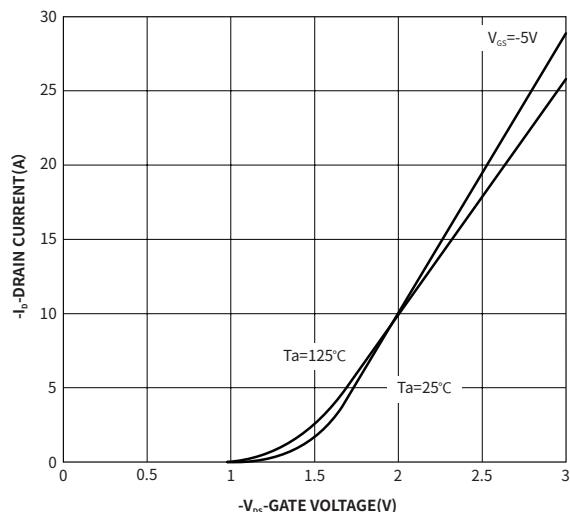


Fig.2 Transfer Characteristics

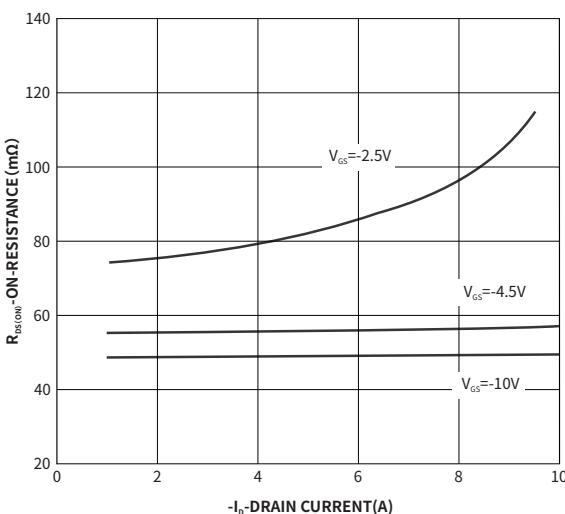


Fig.3 On-Resistance vs. Drain Current and Gate Voltage

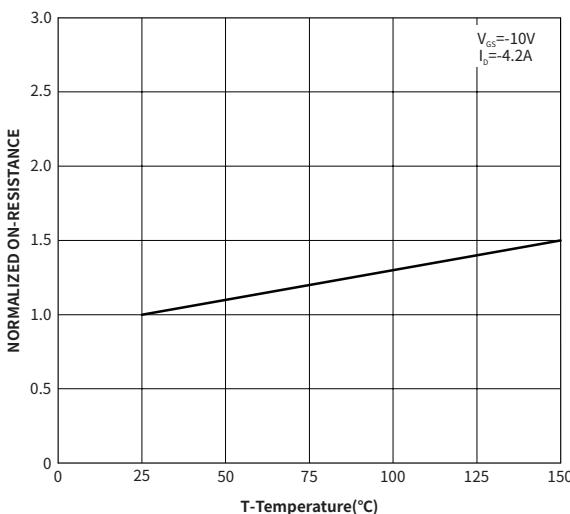


Fig.4 On-Resistance vs. Junction Temperature

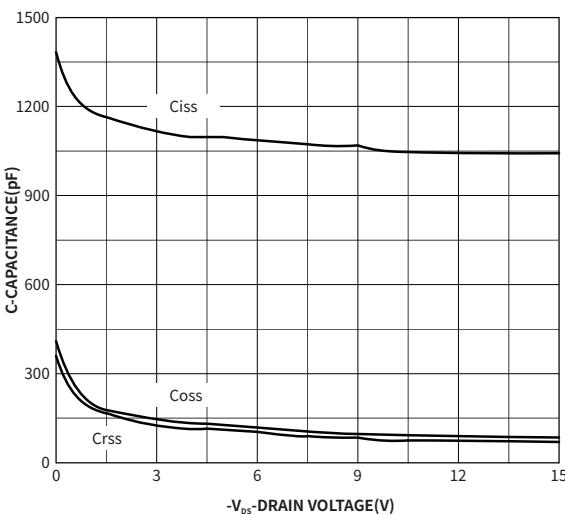


Fig.5 Capacitance Characteristics

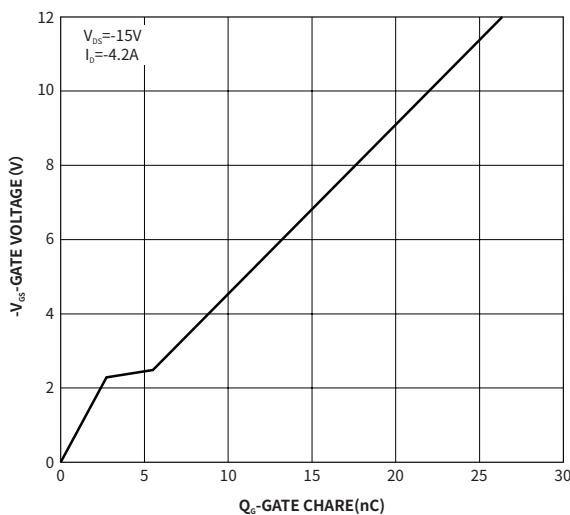


Fig.6 Gate Charge

## ● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

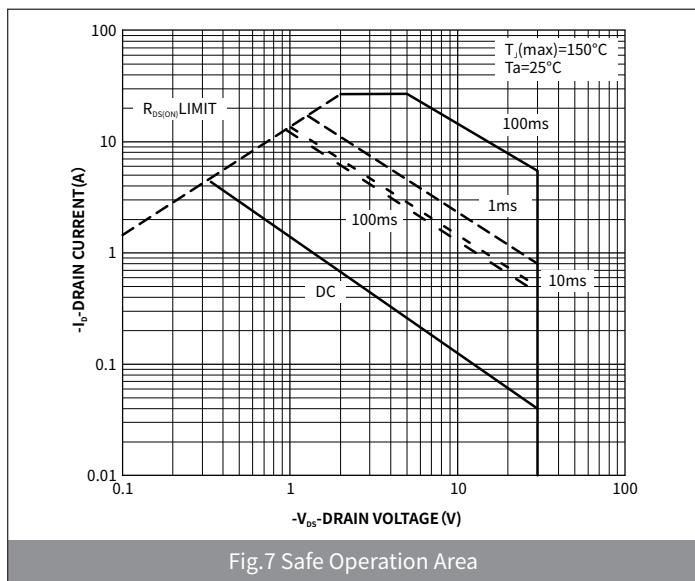


Fig.7 Safe Operation Area

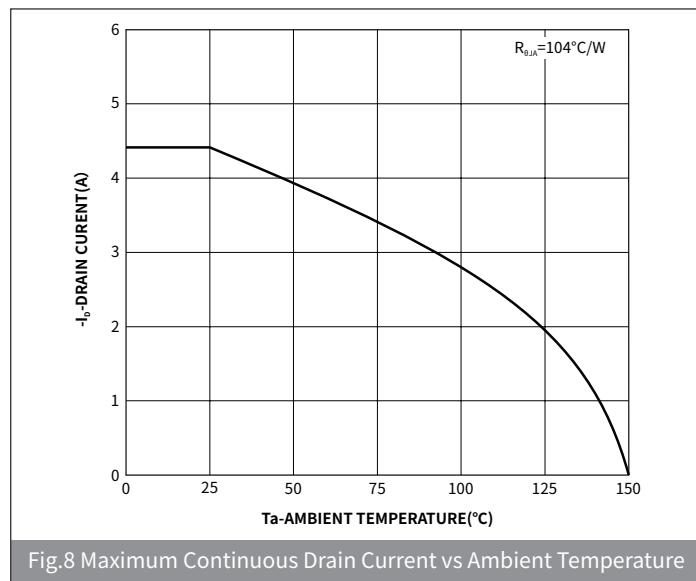


Fig.8 Maximum Continuous Drain Current vs Ambient Temperature

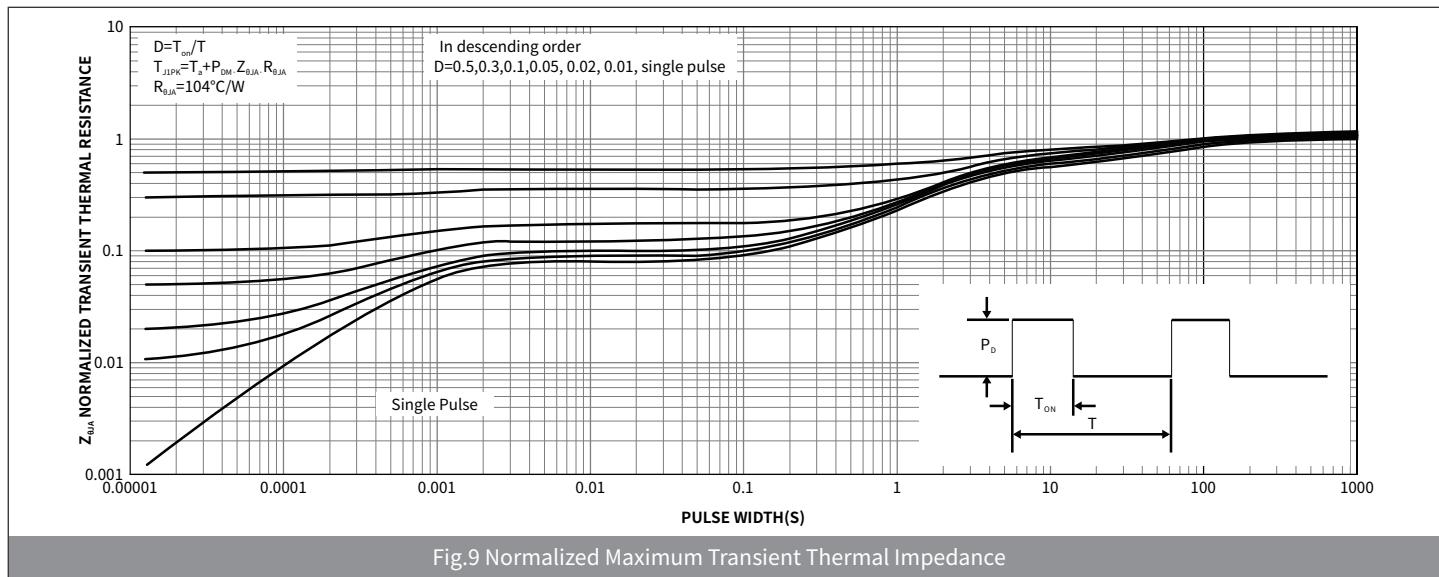
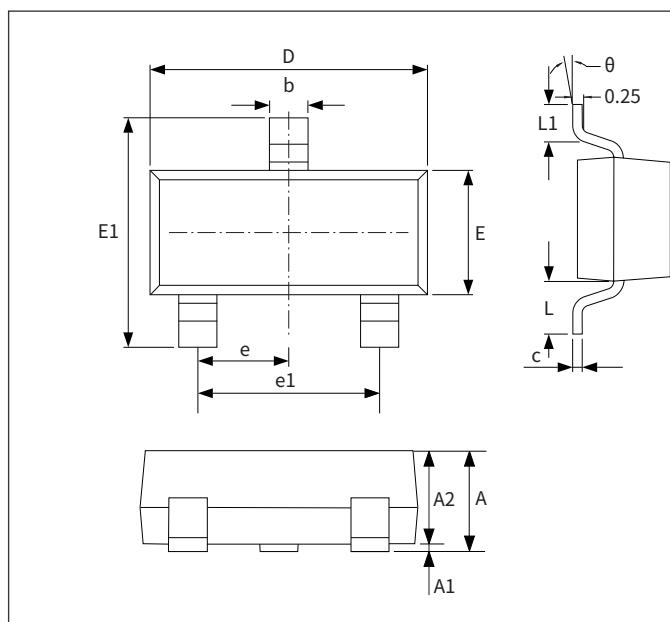


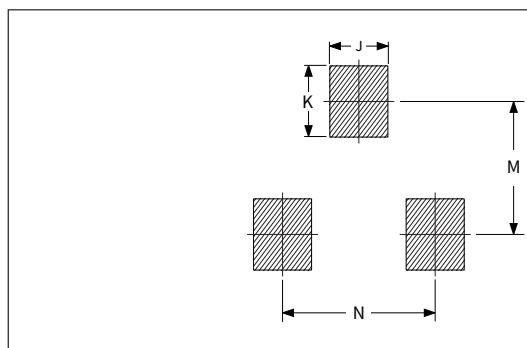
Fig.9 Normalized Maximum Transient Thermal Impedance

### ● Package Outline Dimensions (SOT-23)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.15	0.035	0.045
A1	-	0.10	-	0.004
A2	0.90	1.05	0.035	0.041
b	0.30	0.50	0.012	0.020
c	0.10	0.20	0.004	0.008
D	2.80	3.00	0.110	0.118
E	1.20	1.40	0.047	0.055
E1	2.25	2.55	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.80	2.00	0.071	0.079
L	0.550REF		0.022REF	
L1	0.30	0.50	0.012	0.020
θ	-	8°	-	8°

### ● Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.75	0.85	0.030	0.033
K	0.85	0.95	0.033	0.037
M	1.95	2.05	0.077	0.081
N	1.85	1.95	0.073	0.077